

Bill of Materials

TI DESIGNS

TIDA-00571

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint	Note
1	1	!PCB		Printed Circuit Board	Any	TIDA-00571		
2	1	1	TPS65130RGE	IC, Positive and Negative Output DC-DC Converter	TI	TPS65130RGE	QFN24	
3	10	C1, C18, C19, C20, C21, C22, C23, C24, C25, C28	1uF	CAP, CERM, 1 uF, 10 V, +/- 10%, X7R, 0603	MuRata	GRM188R71A105KA61D	0603	
4	2	C2, C3	4.7uF	CAP, CERM, 4.7 uF, 6.3 V, +/- 10%, X5R, 0805	MuRata	GRM21BR60J475KA11L	0805	
5	1	C4	0.1uF	CAP, CERM, 0.1 uF, 10 V, +/- 10%, X7R, 0402	MuRata	GRM155R71A104KA01D	0402	
6	1	C5	0.01uF	CAP, CERM, 0.01 uF, 16 V, +/- 10%, X7R, 0402	MuRata	GRM155R71C103KA01D	0402	
7	1	C6	10pF	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0402	MuRata	GRM1555C1H100JA01D	0402	
8	1	C7	0.22uF	CAP, CERM, 0.22 uF, 6.3 V, +/- 10%, X5R, 0402	MuRata	GRM155R60J224KE01D	0402	
9	1	C8	4700pF	CAP, CERM, 4700 pF, 50 V, +/- 10%, X7R, 0402	MuRata	GRM155R71H472KA01D	0402	
10	1	C9	12pF	CAP, CERM, 12 pF, 50 V, +/- 5%, C0G/NP0, 0402	MuRata	GRM1555C1H120JA01D	0402	
11	8	C10, C11, C12, C13, C14, C15, C16, C17	4.7uF	CAP, CERM, 4.7 uF, 25 V, +/- 10%, X7R, 1206	MuRata	GRM31CR71E475KA88L	1206	
12	2	C26, C27	2.2uF	CAP, CERM, 2.2 uF, 10 V, +/- 10%, X7R, 0603	MuRata	GRM188R71A225KE15D	0603	
13	2	D1, D2	20V	Diode, Schottky, 20 V, 1 A, POWERMITE	ON Semiconductor	MBRM120ET1G	POWERMITE	
14	2	J1, J3		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	On-Shore Technology	ED555/2DS	7.0x8.2x6.5mm	
15	1	J2		Terminal Block, 6A, 3.5mm Pitch, 6-Pos, TH	On-Shore Technology	ED555/6DS	20.5x8.2x6.5mm	
16	2	JP1, JP2		Header, 100mil, 3x1, Tin, TH	TE Connectivity	5-146278-3	Header, 3x1, 100mil, TH	
17	2	L1, L2	6.8uH	Inductor, Shielded, Ferrite, 6.8 uH, 0.94 A, 0.131 ohm, SMD	TDK	VLCF4018T-6R8NR94-2	4.0x1.8x4.0mm	
18	1	LBL1		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	Brady	THT-14-423-10	PCB Label 0.650"H x 0.200"W	Size: 0.65" x 0.20"
19	1	Q1	-20V	MOSFET, P-CH, -20 V, -3.7 A, SOT-23	Vishay-Siliconix	SI2323DS	SOT-23	
20	1	R1	100	RES, 100, 1%, 0.063 W, 0402	Vishay-Dale	CRCW0402100RFKED	0402	
21	2	R2, R4	180k	RES, 180 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402180KJNED	0402	
22	1	R3	560k	RES, 560 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402560KJNED	0402	
23	1	R5	750k	RES, 750 k, 1%, 0.063 W, 0402	Vishay-Dale	CRCW0402750KFKED	0402	
24	1	R6	10k	RES, 10 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW040210K0JNED	0402	
25	2	R7, R8	0	RES, 0, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04020000Z0ED	0402	

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26	4	R9, R12, R13, R14	0	RES, 0, 5%, 0.1 W, 0603	Yageo America	RC0603JR-070RL	0603	
27	1	R10	43k	RES, 43 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW040243K0JNED	0402	
28	1	R11	24k	RES, 24 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW040224K0JNED	0402	
29	1	U1		Ultra Low-Noise, 250-mA Linear Regulator for RF and Analog Circuits, DQN0004A	Texas Instruments	LP5907SNX-1.8/NOPB	DQN0004A	
30	4	U2, U3, U4, U5		Ultra Low-Noise, 250-mA Linear Regulator for RF and Analog Circuits, DQN0004A	Texas Instruments	LP5907SNX-3.3/NOPB	DQN0004A	
31	1	U6		200mA Low-Noise, High-PSRR Negative Output Low-Dropout Linear Regulators, DBV0005A	Texas Instruments	TPS72301DBV	DBV0005A	

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